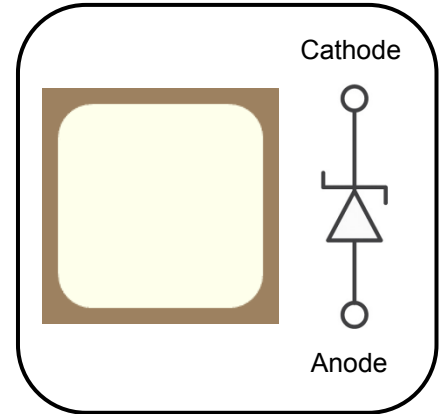


3rd Generation 1200V/20A SiC Schottky Barrier Diode

Features

- Revolutionary semiconductor material - Silicon Carbide (SiC)
- No reverse recovery
- High-speed switching performance
- Temperature-independent switching behavior
- System cost / size savings due to reduced cooling requirements
- Junction temperature range from -55°C to 175°C
- RoHS compliant



Potential Applications

- Industrial power supplies: Industrial UPS
- Battery chargers
- Solar inverters
- Switch mode power supplies



Description

The SDS120J020B3 SiC Schottky Barrier Diode (SBD) has been developed using Sanan's advanced 3rd generation SiC SBD technology with the highest performance and reliability. It registers higher efficiency, higher operation temperature and lower loss and can be operated at higher frequency than Si-based solutions. As to the Schottky structure, it shows no recovery at turn-off and allows a low leakage current with reverse voltage up to 1200V. It can contribute to system miniaturization and achieve lightweight system design. Using RoHS compliant components, it is qualified for use in industrial application.

Product Specifications

Device	V_{RRM}	I_F (135°C)	V_F (25°C)	Q_C
SDS120J020B3	1200V	29A	1.35V	108nC

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Table 1. Maximum Ratings

(T_c = 25°C, unless otherwise specified)

Parameter	Symbol	Value	Unit	Test conditions
Repetitive peak reverse voltage	V _{RRM}	1200	V	T _C = 25°C
Surge peak reverse voltage	V _{RSM}	1200		T _C = 25°C
DC reverse voltage	V _{DC}	1200		T _C = 25°C
Continuous forward current	I _F	63	A	T _C = 25°C
		29		T _C = 135°C
		20		T _C = 155°C
Surge non-repetitive forward current	I _{FSM}	180	A	T _C = 25°C, t _p = 10ms, half sine pulse
Repetitive peak forward current	I _{FRM}	120	A	T _C = 25°C, t _p = 10ms, half sine wave D = 0.1
i ² t value	∫i ² dt	162	A ² s	T _C = 25°C, t _p = 10ms
Operating junction temperature	T _j	-55~175	°C	
Storage temperature	T _{stg}	-55~175	°C	

Table 2. Thermal Resistance

Parameter	Symbol	Values			Unit	Test condition
		Min.	Typ.	Max.		
Thermal resistance from junction to case	R _{th(j-c)}	/	0.56	/	°C/W	

*Thermal Resistance is collected in TO247-2L

Table 3. Static Electrical Characteristics

($T_j = 25^\circ\text{C}$, unless otherwise specified)

Parameter	Symbol	Values			Unit	Test conditions
		Min.	Typ.	Max.		
DC blocking voltage	V_{DC}	1200	/	/	V	$I_R = 100\ \mu\text{A}$
Forward voltage	V_F	/	1.35	1.50	V	$I_F = 20\text{A}$, $T_j = 25^\circ\text{C}$
		/	1.85	2.20		$I_F = 20\text{A}$, $T_j = 175^\circ\text{C}$
Reverse current	I_R	/	3	60	μA	$V_R = 1200\text{V}$, $T_j = 25^\circ\text{C}$
		/	20	320		$V_R = 1200\text{V}$, $T_j = 175^\circ\text{C}$

Table 4. Dynamic Electrical Characteristics

($T_j = 25^\circ\text{C}$, unless otherwise specified)

Parameter	Symbol	Values			Unit	Test conditions
		Min.	Typ.	Max.		
Total capacitance	C	/	1565	/	pF	$V_R = 0\text{V}$, $f = 1\text{MHz}$
		/	101	/		$V_R = 400\text{V}$, $f = 1\text{MHz}$
		/	75	/		$V_R = 800\text{V}$, $f = 1\text{MHz}$
Total capacitive charge	Q_C	/	108	/	nC	$V_R = 800\text{V}$
Capacitance stored energy	E_C	/	31	/	μJ	$V_R = 800\text{V}$

Electrical Characteristic Diagrams

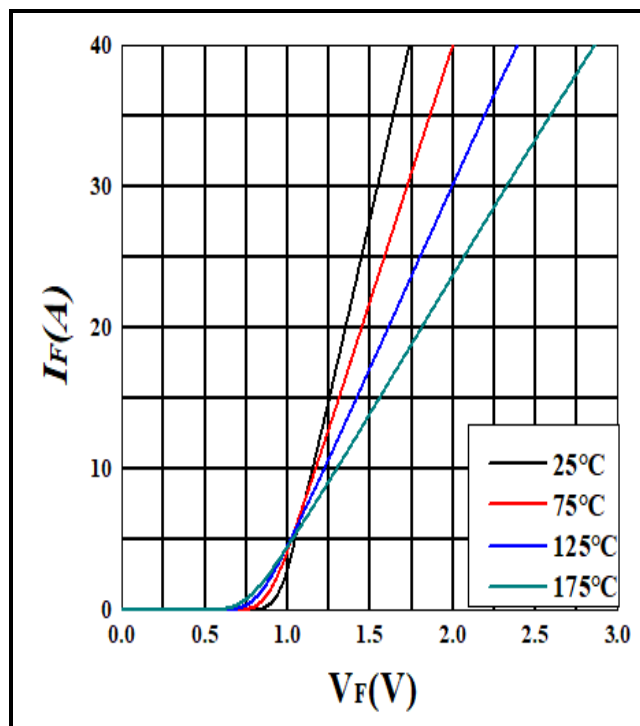


Figure 1. Forward characteristics

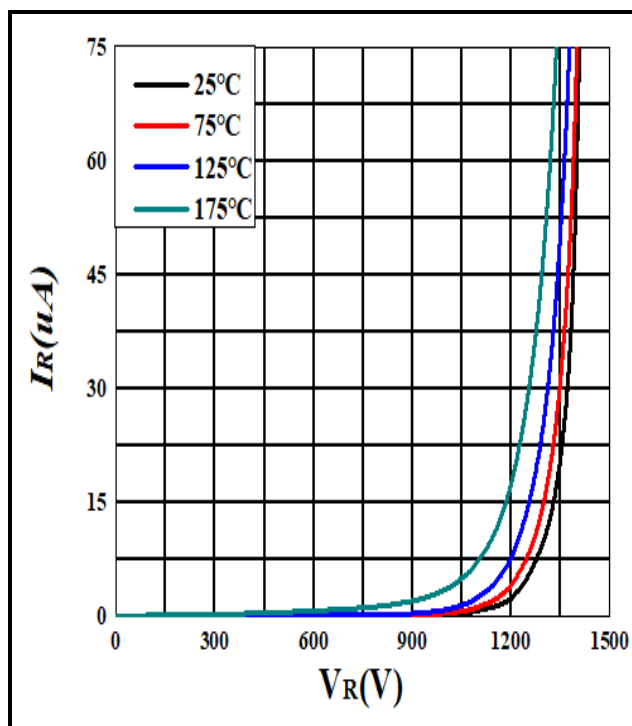


Figure 2. Reverse characteristics

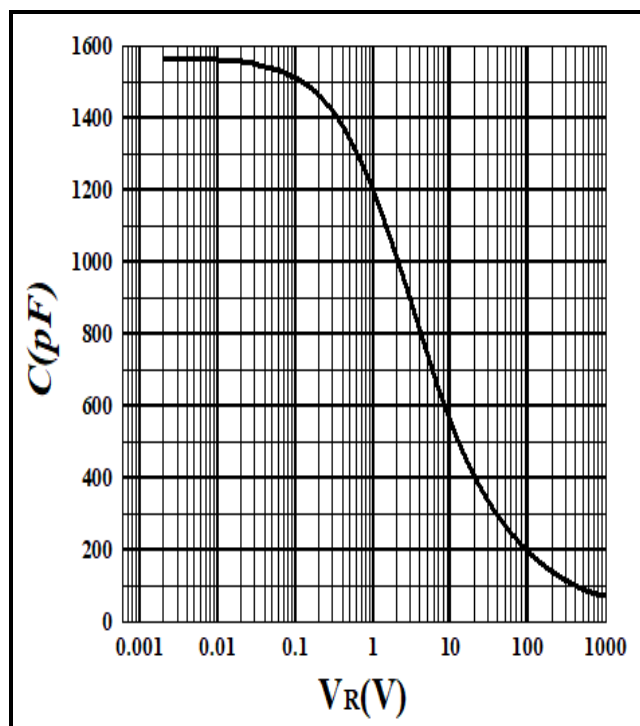


Figure 3. Capacitance vs. reverse voltage

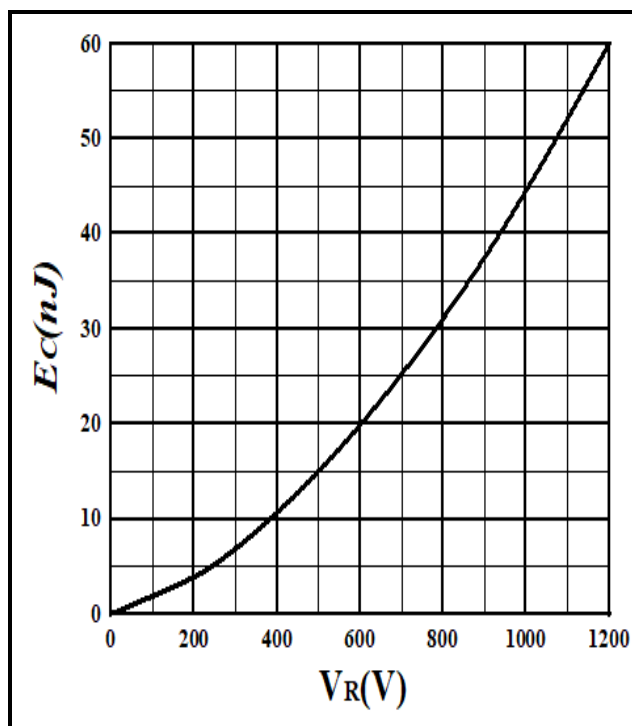


Figure 4. Capacitance stored energy

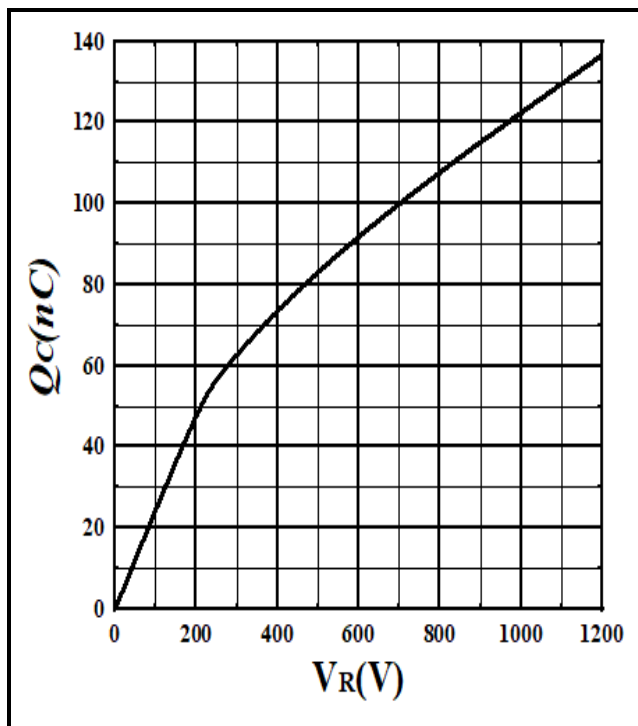


Figure 5. Total capacitance charge vs. reverse voltage

Ordering Information

Part Number	SDS120J020B3
Package	Bare Die
Packing Method	Wafer
RoHS	Yes

Important Notices – Read Carefully

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